

IMAPS Symposium in Review

BY FRANÇOISE VON TRAPP, MANAGING EDITOR

Like going to the IMAPS International Symposium, held this year Oct 9-14 in San Diego. For our industry, it's one of the more comprehensive events, and unlike some of the larger trade shows that expand to include the whole spectrum of the semiconductor industry, it's really focused on packaging.

Events like the press luncheon and the Microelectronics Foundation Dinner and Auction allow for all sorts of industry discussion. The drought of U.S. engineering

graduates, when compared to China, was of notable concern. The Foundation's goal is encourage more youths to consider the engineering sciences. They hope to raise \$1 million for their scholarship fund this year.

Keynote speaker, Irwin Jacobs, Ph.D., co-founder and chairman of the board of Qualcomm, discussed his involvement in High Tech High, a charter school initiative that intends to cultivate an interest in technology at the high school level.

During our visit with NxGen Electronics president Dick Brusnell, he talked about how his vision of mentoring the next-generation engineers was part of the reason he came out of retirement four years ago to start NxGen. The engineering and contract manufacturing company specializes in R&D, design, manufacturing, and test services for the growing miniaturization market.



Irwin Jacobs, Ph.D.; and Mike Ehlert of Barry Industries, IMAPS 2007 president, presided over the press luncheon.



Gregg Taran, director, North America, Datacon, showed me the EVOO 2000 Die Bonder, which features a separate dispensing area with integrated dispenser and a bonding area for die-attach and flip chip applications. Datacon will be celebrating their 20th anniversary in early December.



IMAPS 2006 sponsors, NxGen Electronics, celebrated their 4th anniversary by repositioning the company, expanding their facilities, and launching a new website. Shown here are Tricia W. McGough, marketing manager; Kevin Kron, V.P. sales and operations; and Dick Brusnell, president.



Roupen Kesusseyan, Ph.D., senior scientist, Dupont, was the recipient of the 2006 William D. Ashman Award, which honors individuals who have demonstrated outstanding innovative work and service to IMAPS. Kesusseyan was recognized for his total thick film approach to technology for hermetic packages, which will be instrumental in the future of large-panel display technologies.



Joe Martin, manual wire bonder product marketing manager, Kulicke & Soffa, demonstrates the 4700 Convertible Wire Bonder. This manual benchtop bonding tool provides both wedge-wedge and ball-wedge bonding capabilities. It suits R&D environments, rework, and low-volume production.

We never miss an opportunity to catch up with our Advisory Board members while sampling San Diego's fine Mexican fare. Here we are pictured with Joe Fjelstad, CEO, SiliconPipe, and AP Board member; Vern Solberg, consultant, Surface Mount and Microelectronic Engineering, and SMT Magazine Advisory Board; and Jeffrey C. Demmin, Tessera Technologies, AP contributing editor and Board member.

